

[54] **HEAT SINK FOR INTEGRATED-CIRCUIT
CHIP CARRIER**

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[**] Term: **14 Years**

[21] Appl. No.: **664,258**

[22] Filed: **Oct. 24, 1984**

[52] U.S. Cl. **D13/23**

[58] Field of Search **D13/23; 174/16 HS;
357/81; 165/80.1, 80.2, 80.3, 185**

[56] **References Cited**

U.S. PATENT DOCUMENTS

D. 262,960 2/1982 Johnson et al. D13/23
3,187,812 6/1965 Staver 174/16 HS X

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[57] **CLAIM**

The ornamental design for a heat sink for integrated-circuit chip carrier, substantially as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a heat sink for integrated-circuit chip carrier showing my new design, the broken lines being shown for illustrative purposes only; FIG. 2 is a perspective view thereof, omitting the broken lines for clarity of disclosure;

FIG. 3 is a side elevational view thereof, looking upwardly toward the right in relation to the heat sink as it is shown in FIG. 1;

FIG. 4 is a side elevational view thereof, looking upwardly toward the left in relation to the heat sink as it is shown in FIG. 1;

FIG. 5 is a top plan view thereof; and FIG. 6 is a bottom plan view thereof.

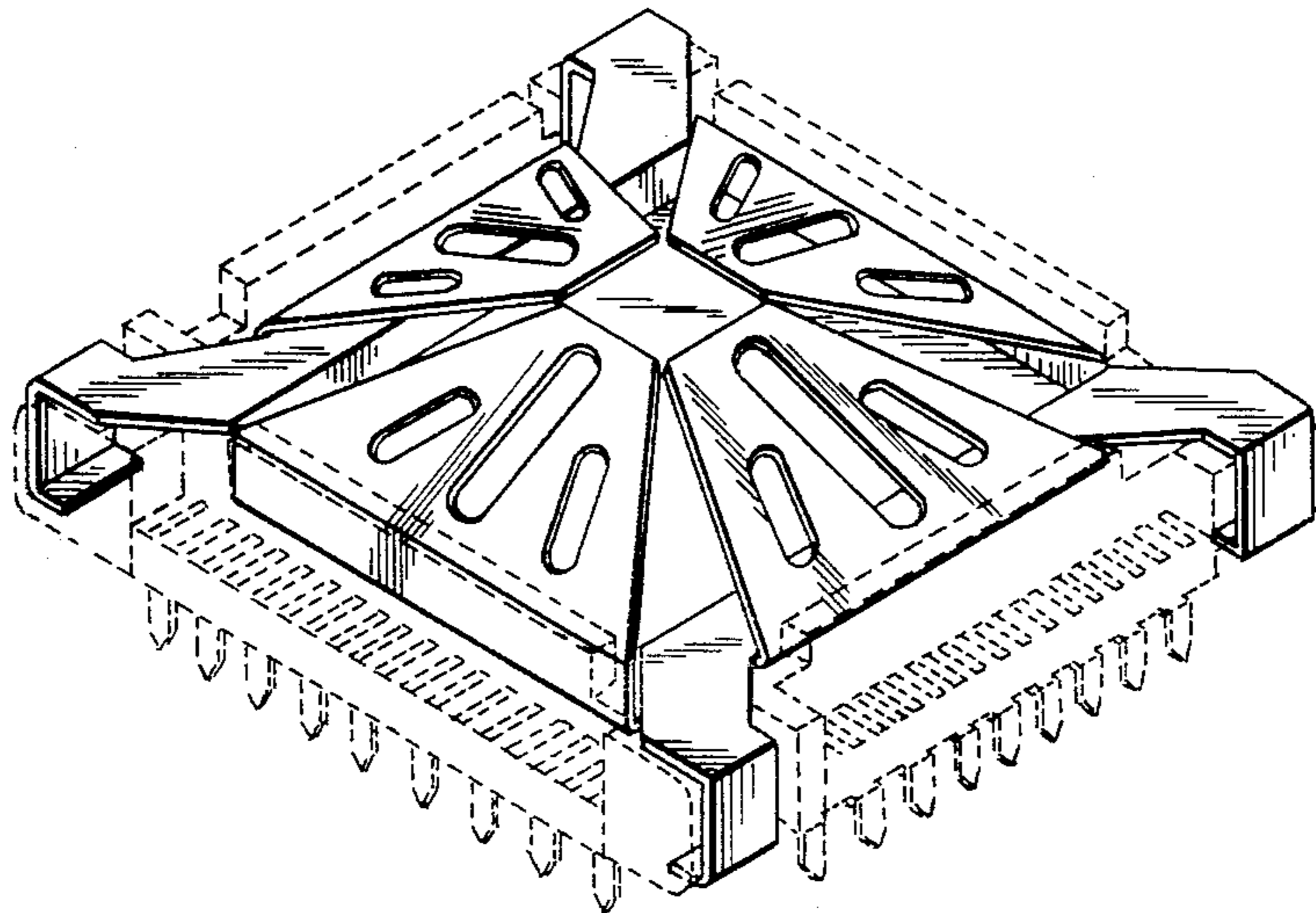


Fig. 1

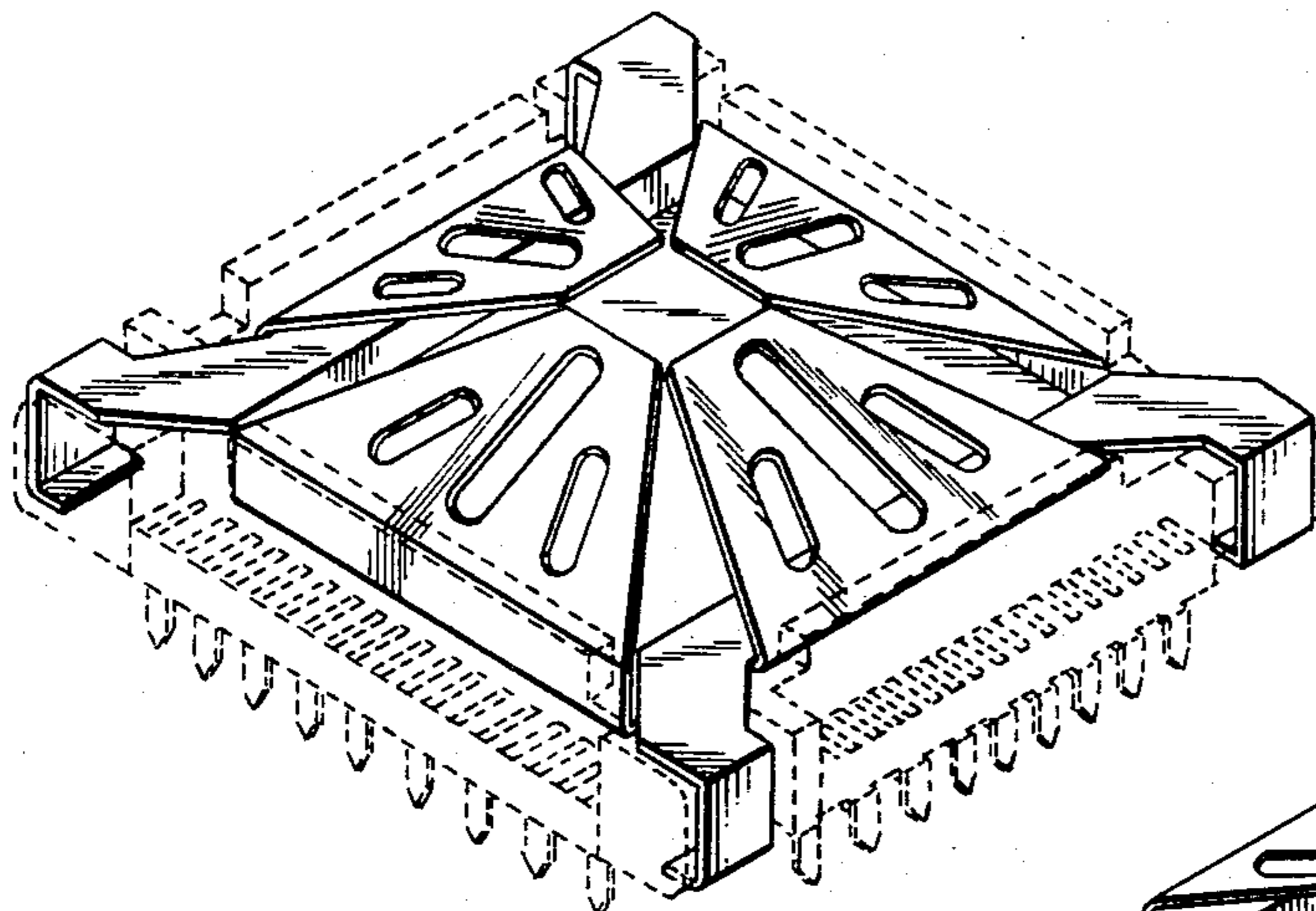


Fig. 2

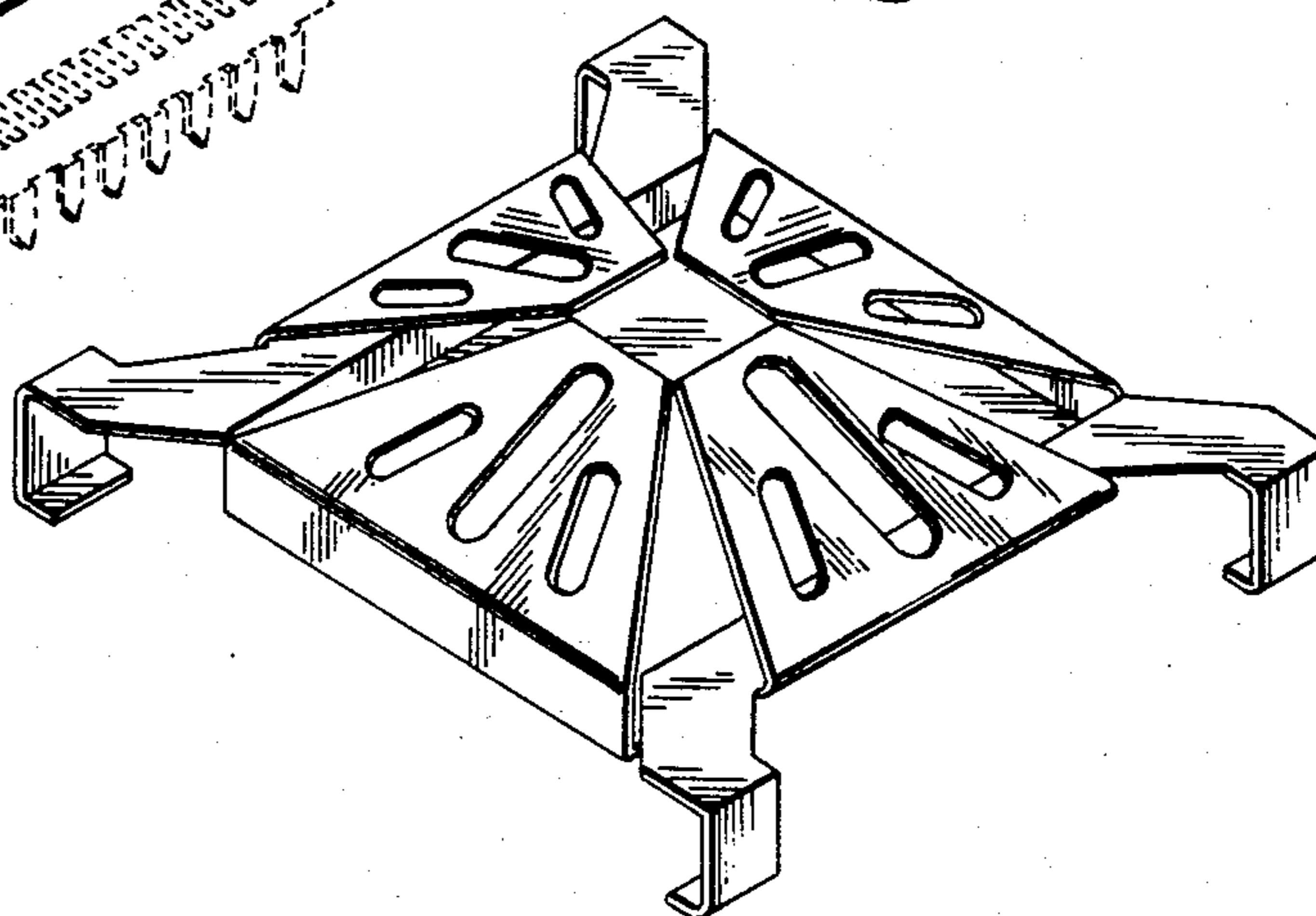


Fig. 3

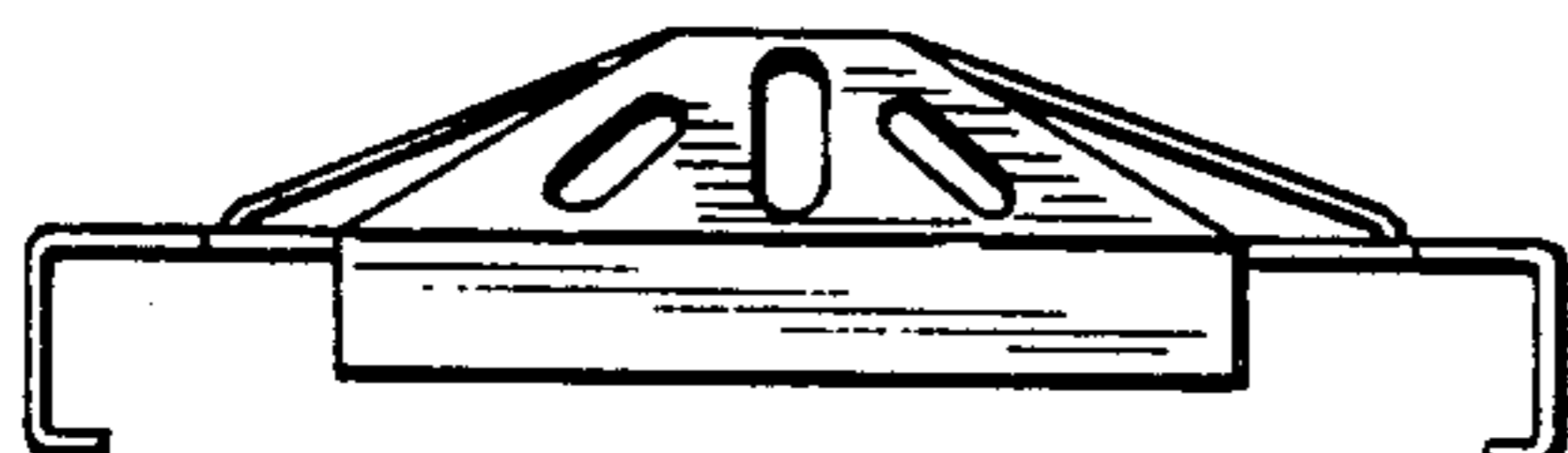


Fig. 4

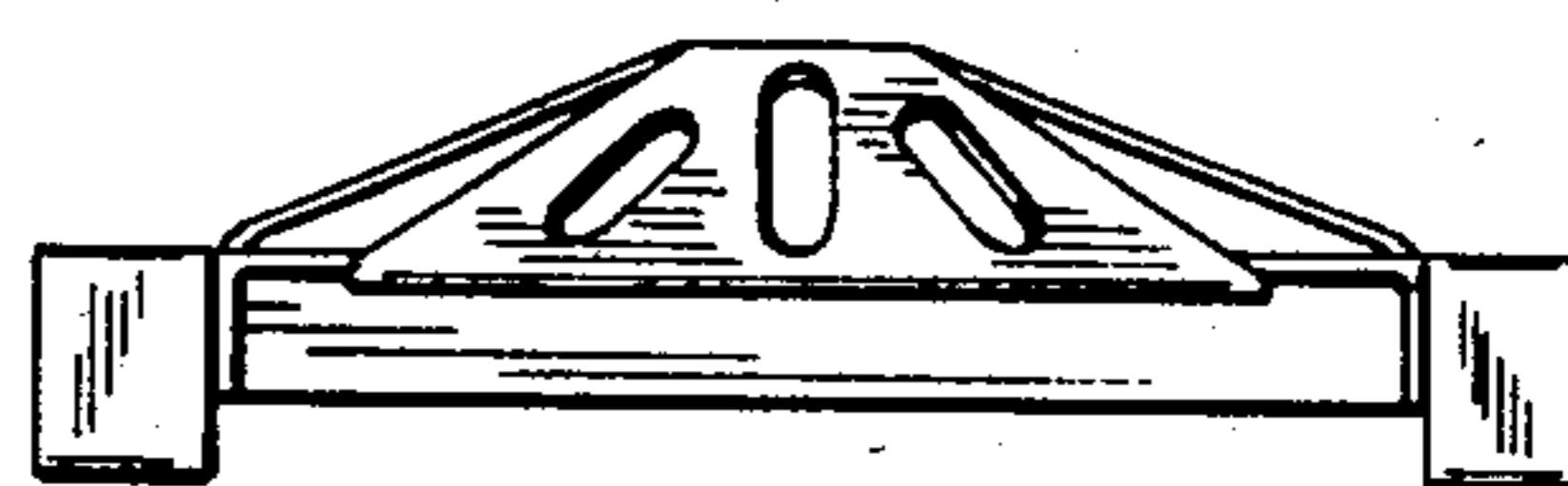


Fig. 5

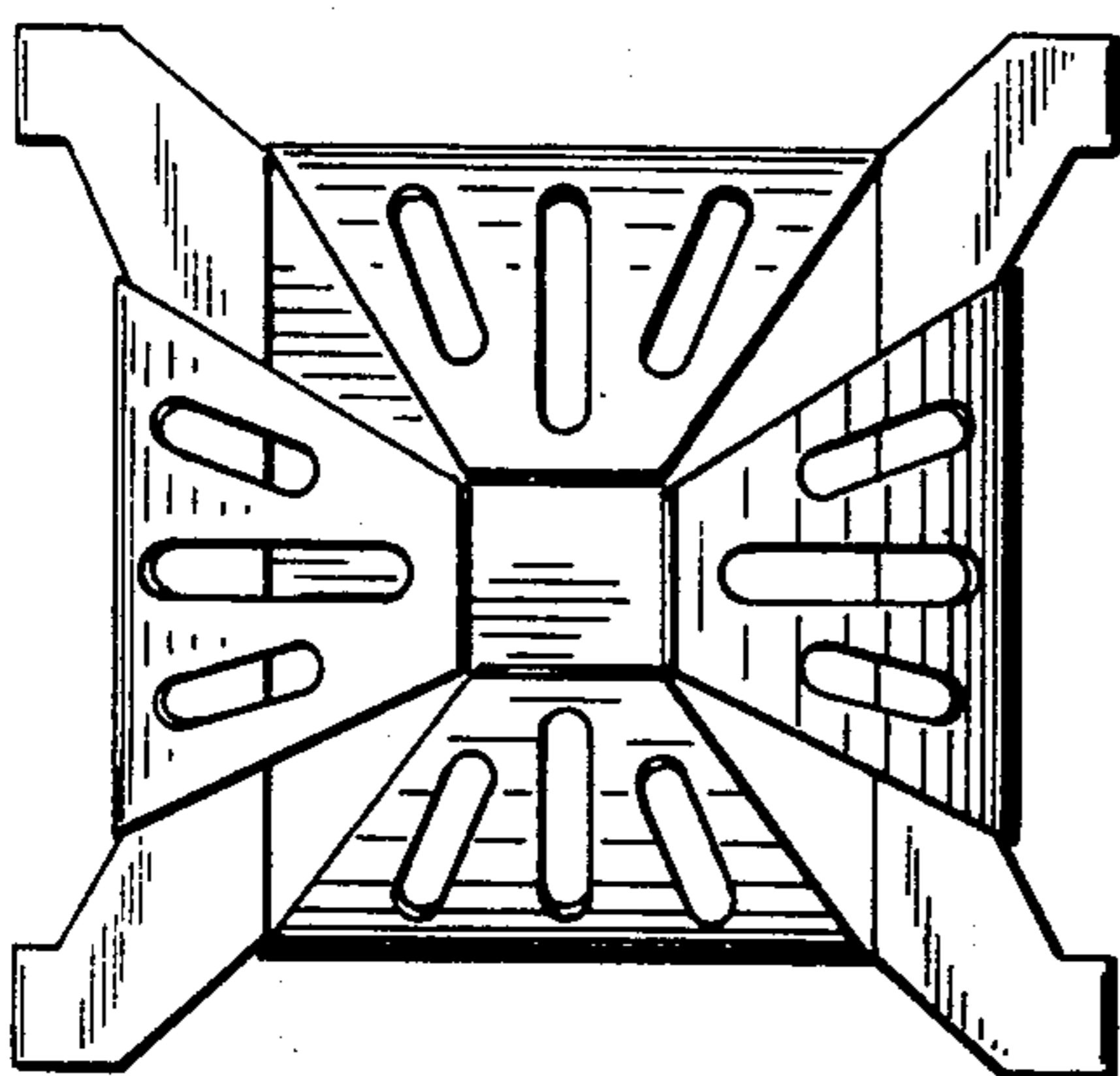


Fig. 6

